

# IM-200; Insulation Metal Substrate

IM-200 is a high thermal resistance filled epoxy with metal base and glass fabric reinforced laminate. It has good thermal conductivity of 2.5 W/mK. It provide high thermal reliability and can pass 260°C Lead free assembly.

## • Features

- Good thermal conductivity@2.5 W/mK.
- RoHS Compliance and suitable for high thermal reliability as Lead free assembly compatible
- Peel Strength > 8 lbs./inch

## • Application

- LED lighting application
- Street lamp and lighting
- Traffic lighting
- Automotive application

Properties	Test Condition	Unit	Typical value
Thermal Conductivity	ISO 22007-2	W/m*K	2.5
Tg /DSC	2.4.25	°C	140
Td /TGA	ASTM D3850	°C	370
Thermal Stress (288 C Solder Dip)	2.4.13.1	minute	Pass
Hi Pot Withstand [VDC]	2.5.7	Volts	4.0
Dielectric Strength [VAC]	2.5.6.2	V/mil	1000
Dielectric Constant (@1MHz)	2.5.5.3	-	5.1
Dissipation Factor (@1MHz)	2.5.5.3	-	0.015
Volume Resistance/ After Moisture	2.5.17.1	MΩ-cm	1.6x10 <sup>11</sup>
Volume Resistance/ E-24/125			-
Surface Resistance/ After Moisture	2.5.17.1	MΩ	2.2x10 <sup>10</sup>
Surface Resistance/ E-24/125			-
Peel Strength [1 oz Cu]	2.4.8	lb/in	7
Comparative Tracking Index (CTI)		V	600
UL Flammability		-	V-0

